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FORM PTO-1595

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U.S. Department of Commerce  
Patent and Trademark Office

JCS11 U.S. PTO  
09/183980  
10/31/98

MPO 10-31-98

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Gonzalo Amador  
Gregory B. Hotchkiss  
Katherine G. Heinen

Additional name(s) attached? \_\_\_Yes \_\_\_X\_\_\_No

2. Name and Address of receiving party(ies):

Name: Texas Instruments Incorporated  
Address: P.O. Box 655474 M/S 3999  
City: Dallas

State: TX Zip: 75265

Additional name(s) attached? \_\_\_Yes \_\_\_X\_\_\_No

3. Nature of Conveyance:

Assignment      \_\_\_ Merger  
\_\_\_ Security Agreement      \_\_\_ Change of Name

\_\_\_ Other \_\_\_\_\_

Execution Date: October 26, 1998

4. Application number(s) or patent number(s): **09/183980**

This document is being filed together with a new application.

Execution date of the application: October 26, 1998

Title: **Wafer-Scale Assembly of Chip-Size Packages**

Docket No.: TI-26059

|   |   |
|---|---|
| A. Patent Application No.(s)                  | B. Patent No.(s)                              |
| Additional numbers attached? ___Yes ___X___No | Additional numbers attached? ___Yes ___X___No |

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gary C. Honeycutt  
Texas Instruments Incorporated  
P.O. Box 655474, MS 39999  
Dallas

State: TX Zip: 75265

6. Number of applications and patents involved: 1

7. Amount of fee enclosed or authorized to be charged: \$40

8. Deposit account number (Attach two copies of this form if paying by deposit account): 20-0668

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

*Gary C. Honeycutt*  
\_\_\_\_\_  
Gary C. Honeycutt

October 30, 1998  
\_\_\_\_\_  
Date

PATENT  
REEL: 9578 FRAME: 0700

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

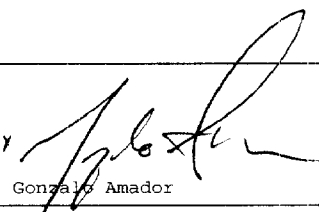
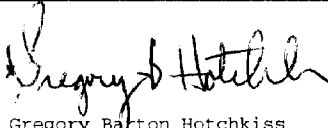
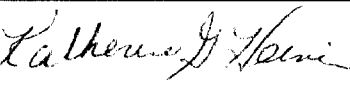
WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 7839 Churchill Way, MS 3999, Dallas, Texas 75251, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

| TITLE OF INVENTION              | Wafer-Scale Assembly of Chip-Size Packages  |  |  |
|---------------------------------|---|--|--|
| SIGNATURE OF INVENTOR AND NAME  | <br>Gonzalo Amador | <br>Gregory Barton Hotchkiss | <br>Katherine G. Heinen |
| DATE OF SIGNATURE               | x 10/19/98  | x 10/19/98   | 10/26/98   |
| RESIDENCE (City, County, State) | Dallas, Dallas County, Texas  | Richardson, Collin County, Texas   | Dallas, Dallas County, Texas   |
| DATE APPLICATION EXECUTED       | x 10/19/98  | x 10/19/98   | 10/26/98   |

After recording Assignment, please return to:

Gary C. Honeycutt  
Texas Instruments Incorporated  
P.O. Box 655474, MS 3999  
Dallas, TX 75265